

REMARKS

Claims 10, 14-15, 45-51 and 54-58 are pending in this application. Claims 47 and 49 have been amended by the present Amendment. Amended claims 47 and 49 do not introduce any new subject matter.

OBJECTIONS TO THE CLAIMS

The Examiner has objected to claims 47 and 49 because of the informalities listed on page 2 of the Office Action. Applicants have amended claims 47 and 49 to correct the informalities as suggested by the Examiner, and respectfully request that the Examiner withdraw the objections to claims 47 and 49.

REJECTION UNDER 35 U.S.C. § 102

Reconsideration is respectfully requested of the rejection of claims 10, 15, 45-47, 50, 51 and 54-58 under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,252,247 ("Sakata").

Claims 10, 45 and 51 essentially recite, *inter alia*, the inter-layer reaction layer/second conductive layer includes inter-metallic compound comprising Al and the inter-metallic compound is formed by depositing a metal layer on the wire and the data wire and annealing the metal layer.

The Examiner maintains that Sakata teaches that the Al compound (e.g., aluminum nitride) within the layer 3 or 8 is an inter-metallic compound, and that Sakata discloses annealing the metal layer. See January 2, 2008 Office Action at 3-5 (citing Sakata, col. 6, lines 1-5, col. 7, lines 18-21, and col. 8, lines 15-19).

However, in contrast to the claimed embodiments, the addition of nitrogen (N) to aluminum (Al), as stated in the cited portions of Sakata, does not form an inter-metallic

compound because nitrogen is a non-metal. Further, Sakata mentions annealing in connection with the addition of nitrogen. Accordingly, annealing is not disclosed for forming an inter-metallic compound. Further, Applicants note that there does not appear to be any other disclosure in Sakata that teaches the addition of another metal to form an inter-metallic compound comprising Al, which is formed by annealing the deposited metal layer.

For at least this reason, Applicants submit that claims 10, 45 and 51 are not anticipated by Sakata.

For at least the reason that claim 15 depends from claim 10, claims 46-47 and 50 depend from claim 45, and claims 54-58 depend from claim 51, claim 15, claims 46-47, 50 and 54-58 are also submitted not to be anticipated by the cited reference.

Accordingly, for at least the above reasons, Applicants respectfully request that the Examiner withdraw the rejection of claims 10, 15, 45-47, 50, 51 and 54-58 under 35 U.S.C. § 102.

REJECTION UNDER 35 U.S.C. § 103

Reconsideration is respectfully requested of the rejection of claims 14 and 48 under 35 U.S.C. § 103(a) as being unpatentable over Sakata in view of U.S. Patent No. 6,444,296 ("Sasaki").

As stated above, Sakata does not disclose the inter-layer reaction layer including inter-metallic compound comprising Al and the inter-metallic compound is formed by depositing a metal layer on the gate wire and the data wire and annealing the metal layer.

Further, Sasaki fails to cure the deficiency in Sakata.

Accordingly, Applicants submit that it would not be obvious to modify Sakata in view of Sasaki to develop the claimed inter-layer reaction layer.

Therefore, Applicants respectfully submit that claims 10 and 45 are patentable over the cited references. For at least the reason that claim 14 depends from claim 10, and claim 48 depends from claim 45, claims 14 and 48 are also submitted to be patentable over the cited references.

As such, Applicants request that the Examiner withdraw the rejection of claims 14 and 48 under 35 U.S.C. § 103.

As such, in view of the foregoing, Applicants respectfully request that the Examiner withdraw the rejection of claims 14 and 48 under 35 U.S.C. § 103.

ALLOWABLE SUBJECT MATTER

Applicants gratefully acknowledge the Examiner's indication that claim 49 would be allowable if rewritten in independent form to include the limitations of the base claim and any intervening claims.

An early and favorable reconsideration is earnestly solicited. If the Examiner has any further questions or comments, the Examiner may telephone Applicants' Attorney to reach a prompt disposition of this application.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Michael F. Morano", written over a horizontal line.

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